zip®

high performance and value

Design

Patented flat technology with external spring construction. Custom and standard product options available

Application Highlights

With .15mm to .8mm solutions, ZIP is great for high density, low profile interposers.

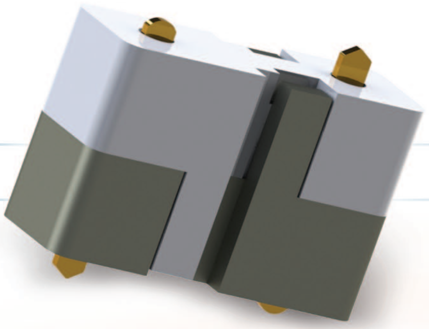
Features & Benefits

- Patented ZIP flat architecture contact
  - Proven reliability in the challenging semiconductor test industry
  - Designs exceeding 40GHz
  - Low Inductance
  - Compressed heights from 1.59mm to 7mm
  - Custom lengths available
  - Allows for tight pitch spacing; down to .3mm inline and array

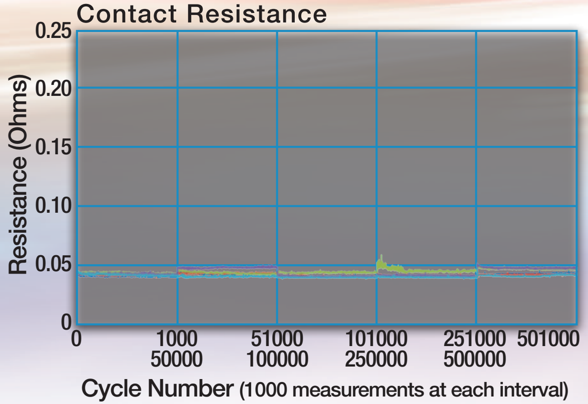
- Patented scrub action
  - Removes oxides from contacts and mates
  - Wipes foreign debris
  - Overcomes failure from plating breakdown

- Off the shelf capability
  - Short run and high volume manufacturing

HYPERcore™
[base material]
option available; page 12



- Detailed tip geometries
  - 2D; single or multitip



Contact Resistance